

AD484

User Manual

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Revision History

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03-29-07	Corrected typos	1.1
04-12-07	Added more details regarding clock synchronization	1.2

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1 Acronyms and related documents

1.1 Acronyms

ADC	Analog to Digital Converter
DAC	Digital to Analog Converter
DCI	Digitally Controlled Impedance
DDR	Double Data Rate
DSP	Digital Signal Processing
EPROM	Erasable Programmable Read-Only Memory
FBGA	Fineline Ball Grid Array
FPDP	Front Panel Data Port
FPGA	Field Programmable Gate Array
JTAG	Join Test Action Group
LED	Light Emitting Diode
LVTTTL	Low Voltage Transistor Logic level
LVDS	Low Differential Data Signaling
LSB	Least Significant Bit(s)
LVDS	Low Voltage Differential Signaling
MGT	Multi-Gigabit Transceiver
MSB	Most Significant Bit(s)
PCB	Printed Circuit Board
PCI	Peripheral Component Interconnect
PCI-e	PCI Express
PLL	Phase Locked Loop
PMC	PCI Mezzanine Card
QDR	Quadruple Data rate
SDRAM	Synchronous Dynamic Random Access memory
SRAM	Synchronous Random Access memory

Table 1: Glossary

1.2 Related Documents

- IEEE Std 1386.1-2001 : IEEE Standard Physical and Environmental Layers for PCI Mezzanine Cards (PMC).
- ANSI/VITA 32-2003 : Processor PMC.
- ANSI/VITA 39-2003 : PCI-X for PMC and Processor PMC.
- ANSI/VITA 42.0-2005 : XMC Switched Mezzanine Card Auxiliary Standard.
- IEEE Std 1386-2001 : IEEE Standard for a Common Mezzanine Card (CMC) Family.
- [Xilinx Virtex-4 user guide](#)
- [Xilinx PCI-X core datasheet](#)
- Xilinx Virtex-4 Rocket I/O guide

1.3 General description

The AD484 is a high performance PMC/XMC digitizer module dedicated to digital signal processing applications with high bandwidth and complex algorithms requirements. The AD484 can interface to a PCI-express, PCI-X and/or PCI bus. In addition to four 125MSPS A/D channels, the AD484 offers fast on-board memory resources and two Virtex-4 FPGAs. Up to 4x 2.5Gbps optical transceivers for serial FPDP or gigabit Ethernet applications are available for communication with external systems. The AD484 is mechanically and electrically compliant to the standard and specifications listed in section 1.2 of this document. The AD484 implements a comprehensive clock circuitry that allows synchronisation among the converters and cascading modules for multiple receiver systems as well as the use of an external reference clock. It provides a complete conversion solution and stands as a platform that can be part of a receive base station.

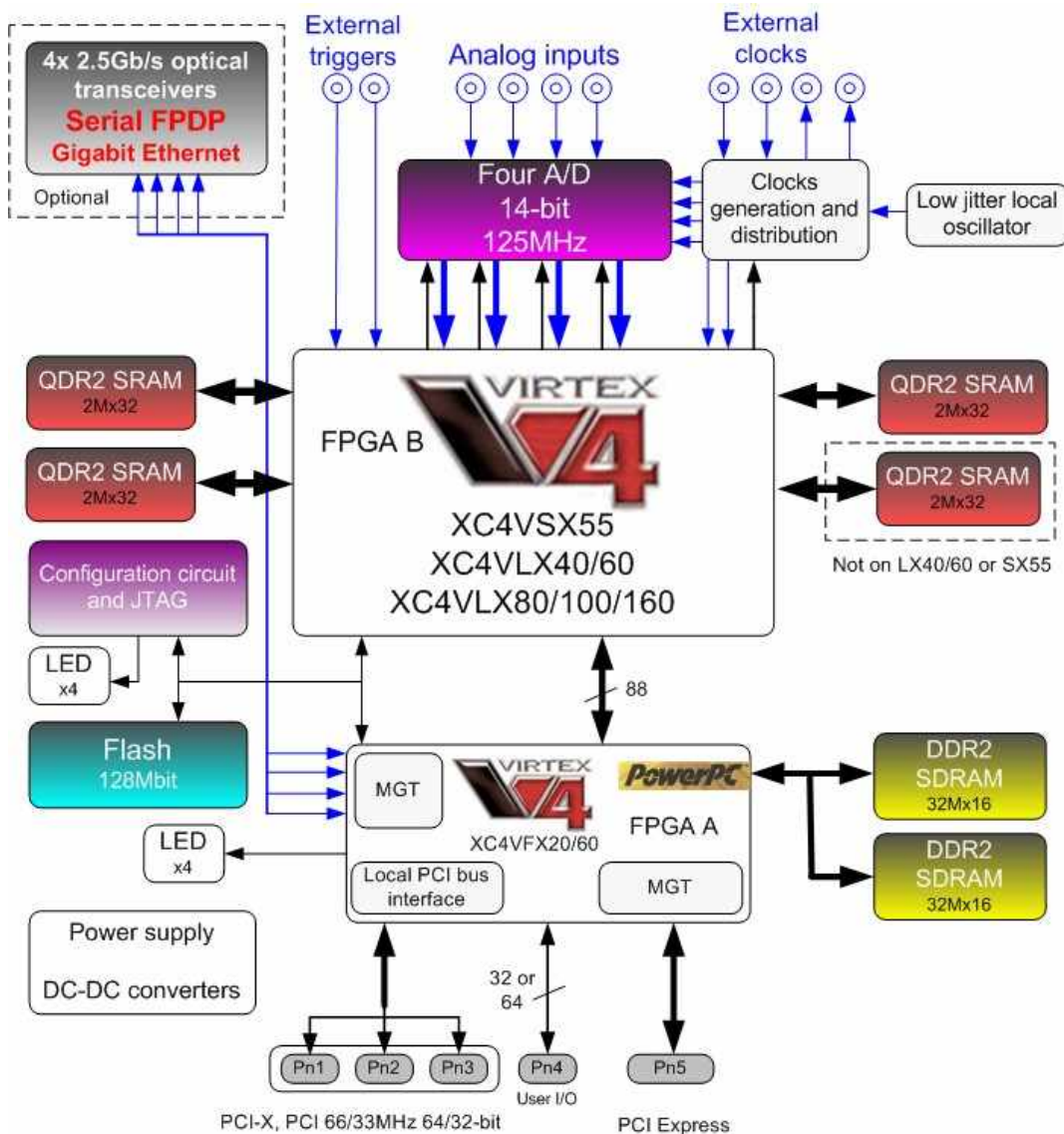


Figure 1: AD484 block diagram

The AD484 converts 4 analogue signals into four 14-bit resolution digital data flows with a sampling frequency up to 125MHz. The clock source can be set to external or internal using the software and firmware settings available to users. Please note that the clock generation on board is using low-jitter clock synthesizers.

2 Installation

2.1 Requirements and handling instructions

- The AD484 must be installed on a motherboard compliant to the IEEE Std 1386-2001 standard for 3.3V PMC or on a motherboard compliant to the XMC Switched Mezzanine Card Auxiliary Standard
- Do not flex the board
- Observe SSD precautions when handling the board to prevent electrostatic discharges.
- Do not install the AD484 while the motherboard is powered up.

2.2 Firmware and software

Drivers, API libraries and a program example working in combination with a pre-programmed firmware for both FPGAs are provided. The AD484 is delivered with an interface to the Xilinx PCI core in the Virtex-4 device A and an example VHDL design in the Virtex-4 device B so users can start digitizing and performing data manipulation right out of the box. For more information about software installation and FPGA firmware, please refer the AD484 Get Started Guide and to the Programmer's guide available online.

3 Design

3.1 FPGA devices

The Virtex-4 FPGA devices interface to the various resources on the AD484 as shown on Figure 1. They also interconnect to each other via 86 general purpose pins and 2 clock pins.

3.1.1 Virtex-4 device A

3.1.1.1 Virtex-4 device A family and package

The Virtex-4 device A is from the Virtex-4 FX family. It can be either an XC4VFX20 or XC4VFX60 in a Fineline Ball Grid array with 672 balls (FF672).

3.1.1.2 Power PC embedded processor

Up to two IBM PowerPC RISC processor cores are available in the Virtex-4 device A. This core can be used to execute C based algorithms and control the logic resources implemented in the FPGA.

3.1.1.3 Virtex-4 device A external memory interfaces

The Virtex-4 device A is connected to a 128Mbytes SDRAM bank with a 32-bit data bus width. This memory resource can be used by the PowerPC core or can serve as data buffer.

3.1.1.4 PCI interface

The Virtex-4 device A interfaces directly to the PCI bus via the PMC Pn1, Pn2 and Pn3 connectors or to the PCI-e bus via the Pn5. An embedded PCI core from Xilinx is used to communicate over the PCI bus with the host system on the motherboard. PCI-e 4 lanes, PCI-X 64-bit 66MHz/133MHz, PCI 64-bit 66MHz and PCI 32-bit 33MHz are supported on the AD484. The bus type must be communicated at the time of the order so the right Virtex-4 device A firmware can be loaded into the flash prior to delivery.

The following performances have been recorded with the AD484 transferring data on the bus:

- **PCI-X 64-bit 133MHz: 750Mbytes/s sustained**
- **PCI-X 64-bit 66MHz: 425Mbytes/s sustained**
- **PCI 32-bit 33MHz: 112Mbytes/s sustained**

The PCI-express 4-lane is using the MGT I/Os on the Virtex-4 device A. Power filtering, low jitter clock and special routing are used to achieve the performances required by this standard. Please refer to the Front Panel Optical transceivers section of this document for more details (3.6).

3.1.1.5 LED

Four LEDs are connected to the Virtex-4 device A. In the default FPGA firmware, the LEDs are driven by the Virtex-4 device B via the Virtex-4 device A/ Virtex-4 device B interface.

The LEDs are located on side 2 of the PCB in the front panel area.

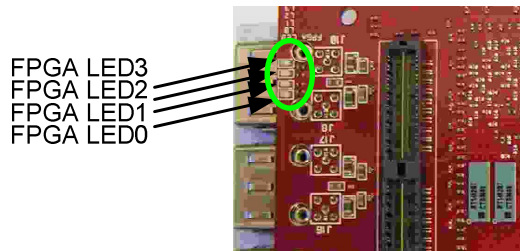


Figure 2: FPGA LED locations

3.1.1.6 Pn4 user I/O connector

The Pn4 connector is wired to the Virtex-4 device A. The 32 lower bits are available only if an XC4VFX60 device is mounted on board. The 32 higher bits are available only if PCI 32-bit is used and only if specified at the time of order.

All signals are user-defined 3.3V LVTTLL./LVCMOS.

Connector pin	Signal name	FPGA pin		FPGA pin	Signal name	Connector pin
1	Pn4_IO0	M9		M10	Pn4_IO1	2
3	Pn4_IO2	N11		M11	Pn4_IO3	4
5	Pn4_IO4	N7		N8	Pn4_IO5	6
7	Pn4_IO6	N6		P6	Pn4_IO7	8
9	Pn4_IO8	P10		P11	Pn4_IO9	10
11	Pn4_IO10	P9		N9	Pn4_IO11	12
13	Pn4_IO12	R8		P8	Pn4_IO13	14
15	Pn4_IO14	R6		R7	Pn4_IO15	16
17	Pn4_IO16	N21		M21	Pn4_IO17	18
19	Pn4_IO18	M20		M19	Pn4_IO19	20
21	Pn4_IO20	P19		N19	Pn4_IO21	22
23	Pn4_IO22	N18		N17	Pn4_IO23	24
25	Pn4_IO24	P16		N16	Pn4_IO25	26
27	Pn4_IO26	R18		P18	Pn4_IO27	28
29	Pn4_IO28	P21		P20	Pn4_IO29	30
31	Pn4_IO30	R17		R16	Pn4_IO31	32
33	Pn4_IO32	L9		M5	Pn4_IO33	34
35	Pn4_IO34	L5		AD11	Pn4_IO35	36
37	Pn4_IO36	AD10		L4	Pn4_IO37	38
39	Pn4_IO38	L3		AB11	Pn4_IO39	40
41	Pn4_IO40	AC11		M4	Pn4_IO41	42
43	Pn4_IO42	N4		T9	Pn4_IO43	44
45	Pn4_IO44	T8		P5	Pn4_IO45	46
47	Pn4_IO46	R5		AA10	Pn4_IO47	48
49	Pn4_IO48	AB10		P4	Pn4_IO49	50
51	Pn4_IO50	R3		W10	Pn4_IO51	52
53	Pn4_IO52	Y10		N3	Pn4_IO53	54
55	Pn4_IO54	P3		U6	Pn4_IO55	56
57	Pn4_IO56	U5		T4	Pn4_IO57	58
59	Pn4_IO58	T3		U7	Pn4_IO59	60
61	Pn4_IO60	V6		U4	Pn4_IO61	62
63	Pn4_IO62	V4		U9	Pn4_IO63	64

Table 2 : Pn4 pin assignment

3.1.2 Virtex-4 device B

3.1.2.1 Virtex-4 device B family and package

The Virtex-4 device B is dedicated to interfacing to the A/D circuitry and can also perform Digital Signal Processing algorithms. It is available in the Virtex-4 SX or LX family devices and is packaged in a 1148-ball Fineline Ball Grid array. In terms of logic and dedicated DSP resources, The FPGA B can be chosen in 5 different sizes: SX55, LX40, LX60, LX80, LX100 and LX160.

3.1.2.2 Virtex-4 device B external memory interfaces

The Virtex-4 device B interfaces to four 8Mbytes QDR2 SRAM devices with 32-bit data bus, Please note that the four QDR2 SRAM devices are only available with the LX80, LX100 and LX160 devices. For smaller Virtex-4 FPGAs (LX40, LX60 and SX55) only three QDR2 SRAM devices are connected to the FPGA.

3.2 FPGA devices configuration

3.2.1 Flash storage

The FPGA firmware is stored on board in a flash device. The 128Mbit device is partly used to store the configuration for both FPGAs. In the default CPLD firmware configuration, the Virtex-4 devices A and B are directly configured from flash if a valid bitstream is stored in the flash for each FPGA. The flash is pre-programmed in factory with the default firmware example for both FPGAs.

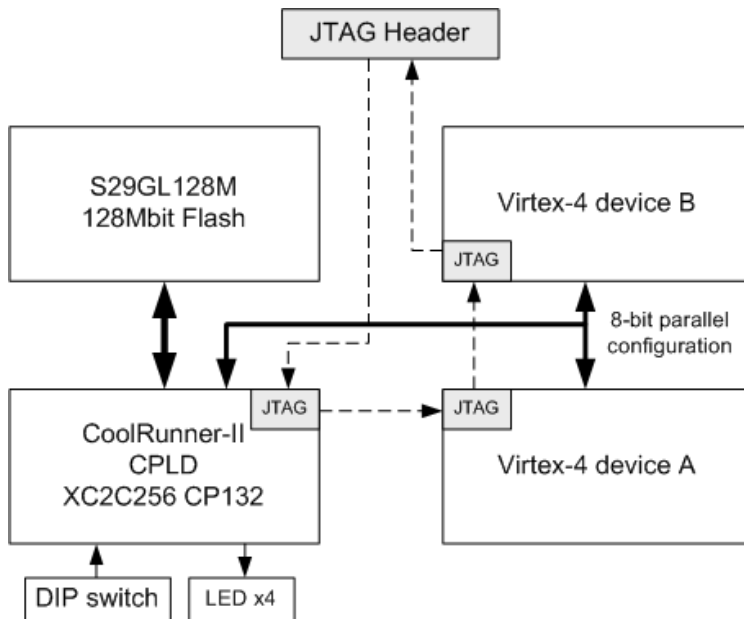


Figure 3 : Configuration circuit

3.2.2 CPLD device

As shown on Figure 2, a CPLD is present on board to interface between the flash device and the FPGA devices. It is of type CoolRunner-II. The CPLD is used to program and read the flash. The data stored in the flash are transferred from the host motherboard via the PCI bus to the Virtex-4 device A and then to the CPLD that writes the required bit stream to the storage device. A 31.25 MHz clock connects to the CPLD and is used to generate the configuration clock sent to the FPGA devices. At power up, if the CPLD detects that an FPGA configuration bitstream is stored in the flash for both FPGA devices, it will start reading programming the devices in SelecMap mode.

Do NOT reprogram the CPLD without 4DSP approval

The CPLD configuration is achieved by loading with a Xilinx download cable a bitstream from a host computer via the JTAG connector. The FPGA devices configuration can also be performed using the JTAG.

3.2.2.1 DIP Switch

A switch (J1) is located next to the JTAG programming connector (J6) see Figure 4. The switch positions are defined as follows:

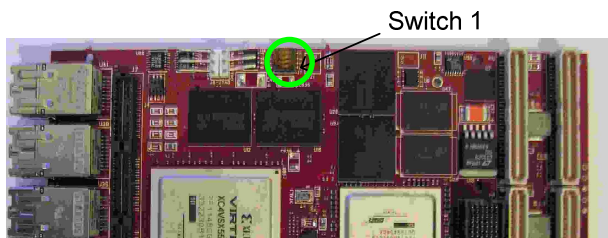


Figure 4: switch (J1) location

Sw1	OFF	Default setting. The Virtex-4 device A configuration is loaded from the flash at power up.
	ON	Virtex-4 device A safety configuration loaded from the flash at power up. To be used only if the Virtex-4 device A cannot be configured or does not perform properly with the switch in the OFF position.
Sw2		Reserved
Sw3		Reserved
Sw4		Reserved

Table 3: Switch description

3.2.2.2 LED and board status

Four LEDs connect to the CPLD and give information about the board status.

LED 0	Flashing	FPGA A or B bitstream or user_ROM_register is currently being written to the flash
	ON	FPGA A not configured
	OFF	FPGA A configured
LED 1	Flashing	FPGA A or B bitstream or user_ROM_register is currently being written to the flash
	ON	FPGA B not configured
	OFF	FPGA B configured
LED 2	Flashing	The Virtex-4 device A has been configured with the safety configuration bitstream programmed in the flash at factory. Please write a valid Virtex-4 device A bitstream to the flash.
	ON	Flash is busy writing or erasing
	OFF	Flash device is not busy
LED 3 LED 3	ON	CRC error. Presumably a wrong or corrupted FPGA bitstream has been written to the flash. Once on this LED remains on
	OFF	No CRC error detected

Table 4: LED board status

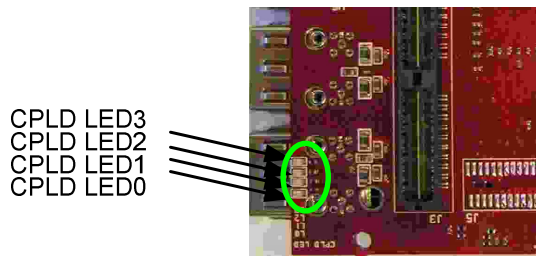


Figure 5: CPLD LED locations

3.2.3 JTAG

A JTAG connector is available on the AD484 for configuration purposes. The JTAG can also be used to debug the FPGA design with the Xilinx Chipscope.

The JTAG connector is located on side 1 of the PCB in front (see Figure 6).

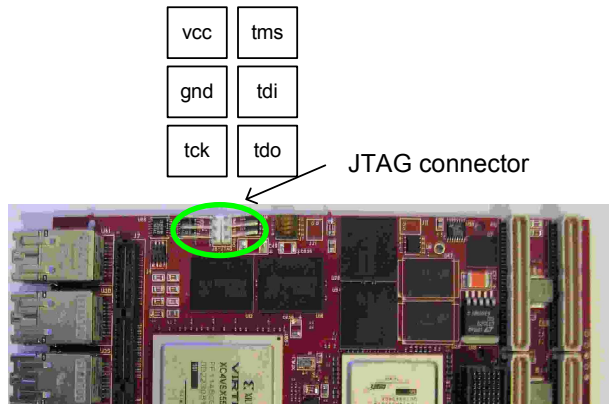


Figure 6: JTAG connector (J6) location

The JTAG connector pinout is as follows:

Pin #	Signal	Signal	Pin #
1	1.8V	TMS	4
2	GND	TDI	5
3	TCK	TDO	6

Table 5 : JTAG pin assignment

3.3 Clock tree

The AD484 clock architecture offers an efficient distribution of low jitter clocks. In addition to the PCI Express bus, the MGT reference clocks of 106.25MHz and 125MHz (Epson EG2121CA) make it possible to implement several standards over the MGT I/Os connected to the optical transceivers.

Both FPGAs receive a low jitter 125MHz clock. A low jitter programmable clock able to generate frequencies from 62.5MHz to 255.5MHz in steps of 0.5MHz is also available. This clock management approach ensures maximum flexibility to efficiently implement multi-clock domains algorithms and use the memory devices at different frequencies. Both clock buffer devices (CDM1804) and the frequency synthesizer (ICS8430-61) are controlled by the Virtex-4 device A.

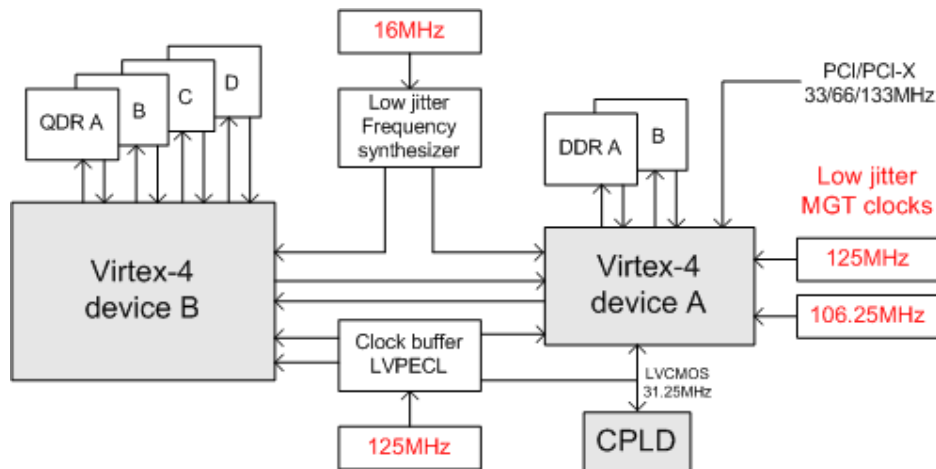


Figure 7 : Clock tree

3.4 Memory resources

3.4.1 QDR2 SRAM

Four independent QDR2 SRAM devices are connected to the Virtex-4 device B. The QDR2 SRAM devices available on the AD484 are 2M words deep (8Mbytes per memory device).

Please note that only three QDR SRAM devices are available to the user if the XC4VLX40, XC4VLX60 or XC4VSX55 FPGA device is mounted on board.

3.4.2 DDR2 SDRAM

Two 16-bit DDR2 SDRAM devices of 128MBytes each are connected to Virtex-4 device A. The two memories share the same address and control bus and have their own data bus. This memory resource can be accessed by the PowerPC processor in the Virtex-4 device A or can be used as a data buffer for custom user logic.

3.5 A/D inputs and outputs main characteristics

Analogue inputs	
Input voltage range	AC coupled option. 2.4 Vp-p (11.5 dbm –50 Ohm) Full scale - AC coupled via RF transformer. DC coupled option. 1.15 Vp-p (Gain amplifier 6dB) centered around 0. DC coupled via amplifier. Gain can be adjusted to a required input amplitude centered around 0. Minimum gain 6dBs, which should allow input swing +/-0.575V as full scale.
Impedance	ADC single-ended inputs are to be connected to a 50Ω source. Source impedance matching implemented between RF transformers and ADC.
Bandwidth	ADC bandwidth: 750 MHz.
External Reference input	
Input voltage level	0.5 – 3.3 Volts peak-to-peak (AC-coupled)
Input impedance	50-Ohm (Termination implemented at the connector)
Frequency range	0-100MHz
External Reference output	
Output voltage level	1.6 Volts peak-to-peak (AC-coupled)
Output impedance	50-Ohm (Termination implemented at the connector)
External sampling clock input	
Input voltage level	0.5 – 3.3 Volts peak-to-peak (AC-coupled)
Input format	Single-ended or differential on option (3.3V LVPECL).
Frequency range	10-125MHz
External Trigger inputs	
Format	DC-coupled and Single-ended (Termination implemented at the connector). Differential on option (3.3 V PECL).
Input Voltage range	1.5-3.3 Volts peak-to-peak.
Impedance	50-ohm
Frequency range	62.5MHz maximum
ADC Output	
Output Data Width	14-bit
Data Format	2's Complement or offset binary (Changeable via control register)
SFDR	82dBs maximum (manufacturer)
SNR	70dBs maximum (manufacturer)
Maximum Sampling Frequency	125MHz.

Table 6: AD484 A/D characteristics

3.5.1 Analog inputs

The module is built around four TI ADS5500 14-bit sampling analog-to-digital. ADCs: Analog data enters the module via four SMA connectors on the front panel, one for each channel. Both signals are then conditioned (AC coupling as standard via RF transformers; DC optional via Texas Instrument amplifier THS4509) before being digitized.

3.5.2 Clock input and reference clock distribution

The ADC devices get their own sampling clock, which can be either on-board generated or from an external reference or an external clock, common to all ADCs via an SMA connector on the front panel. All samplings clocks are generated by the same chip. It allows having them all synchronized to a single reference clock. The on-board clock uses the VCXO locked on an on-board 10MHz reference. The reference clock also can be external. In that case the VCXO is still used. It is also possible to input an external clock that is directly used to sample the analog signals. In all cases, all sampling clocks are synchronized to the same clock source.

3.5.3 Multi-module Synchronization

Several AD484 cards can be cascaded and still be synchronized since either the external reference or the external clock can be passed to the next module in the chain. The external reference goes through a 0-delay buffer and is then output via an SMA connector on the front panel. Please note that synchronisation is in frequency and not in phase.

3.6 Front Panel optical transceivers

Four 2.5Gb/s optical transceivers (LTP-ST11M) are available on the AD484 in the front panel area. They are connected to the MGT I/Os of the Virtex-4 device A. Infiniband protocols as well as Gigabit Ethernet and Fibre channel (sFPDP) can be implemented over the transceivers. Lower rate optical transceivers (2.125Gb/s and 1.0625Gb/s) are available in the same form factor.

Two low jitter clocks (106.25MHz and 125MHz) are directly connected to the MGT clock inputs so multi-rate applications can be implemented on the AD484.

The MGT banks have power supplies independent from the digital supply provided to the FPGAs in order to insure low noise and data integrity. The LT1963 device will be used to generate the 1.2V, 1.5V and 2.5V necessary for the MGT to operate. The power filtering network includes a 220nF decoupling capacitor and ferrite bead (MP21608S221A) per power pin.

The signal differential pairs are routed on a specific inner layer with one reference GND plane on each side of the layer stack up.

The optical transceivers are an ideal communication link to transfer digitized and processed data to a remote system (eg, storage system) by offering an aggregate bandwidth of 1.25GBytes/s.

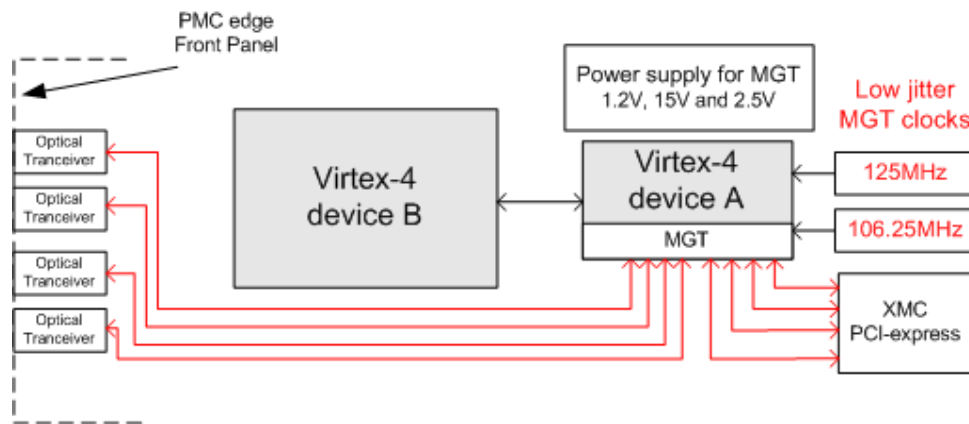


Figure 8: Optical transceivers

4 Power requirements

The power is supplied to the AD484 via the PMC and/or XMC connectors. Several DC-DC converters generate the appropriate voltage rails for the different devices and interfaces present on board.

The AD484 power consumption depends mainly on the FPGA devices work load. By using high efficiency power converters, all care has been taken to ensure that power consumption will remain as low as possible for any given algorithm.

After power up the AD484 typically consumes 5W of power. For precise power measurements it is recommended to use the Xilinx power estimation tools for both FPGA A and B. The maximum current rating given in the table below is the maximum current that can be drawn from each voltage rail in the case resources are used to their maximum level.

Device/Interface	Voltage	Maximum current rating
DCI and memory reference voltage	0.9V	5 A
Virtex-4 device A & B core	1.2V	12A
QDR2, DDR2 SDRAM core and I/O banks, Virtex-4 devices I/O banks	1.8V	10A
Virtex-4 device B I/O bank connected to the front panel daughter card	1.8V/2.5/3.3V	1.5A
Virtex-4 device A I/O bank connected to the PCI bus, Flash, CPLD, front Panel I/O daughter card, A/D circuitry	3.3V	4A
MGT power supply	1.2V, 1.5V, 2.5V	1.7A, 0.5A, 0.01A respectively

Table 7 : Power supply

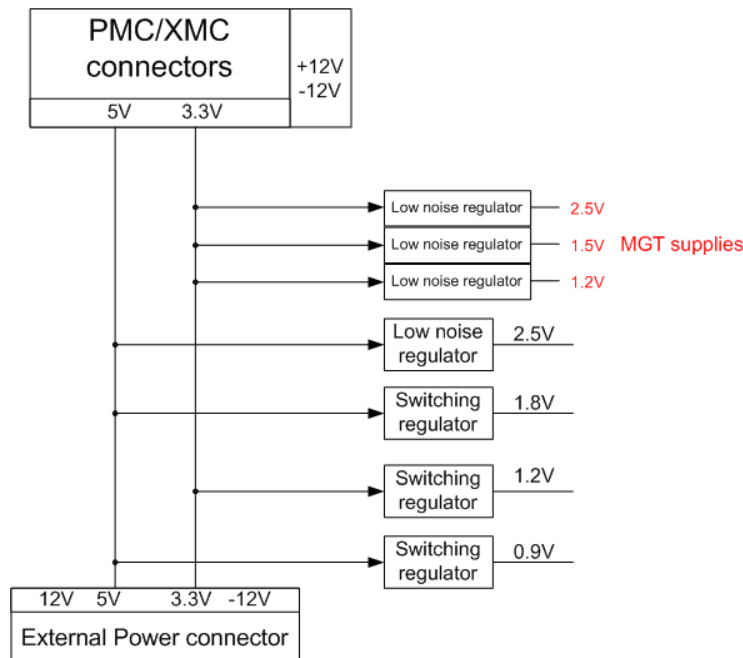


Figure 9 : Power supply

An ADT7411 device is used to monitor the power on the different voltage rails as well as the temperature. The ADT7411 data are constantly passed to the Virtex-4 device A. Measurements can be accessed from the host computer via the PCI bus. A software utility delivered with the board allows the monitoring of the voltage on the 2.5V, 1.8V, 1.2V and 0.9V rails. It also displays the Virtex-4 device B junction temperature.

4.1 External power connector for stand alone mode

An external power connector (J2) is available on side 2 of the PMC, next to the PMC connectors. It is used to power the board when it is in stand alone mode. This is a right angled connector and it will be mounted on board only if the card is ordered in its stand alone version (AD484-SA). The height and placement of this connector on the PCB breaches the PMC specifications and the module should not be used in an enclosed chassis compliant to PMC specifications if the external power connector is present on board.

Do not connect an external power source to J2 if the board is powered via the PMC connectors. Doing so will result in damaging the board.

The external power connector is of type Molex 43045-1021. Each circuit can carry a maximum current of 5A. The connector pin assignment is as follows:

Pin #	Signal	Signal	Pin #
1	3.3V	3.3V	2
3	5V	5V	4
5	GND	GND	6
7	GND	GND	8
9	-12V	12V	10

Table 8 : External power connector pin assignment

5 System Side view

The following diagram shows a side view of the AD484 mounted a motherboard.

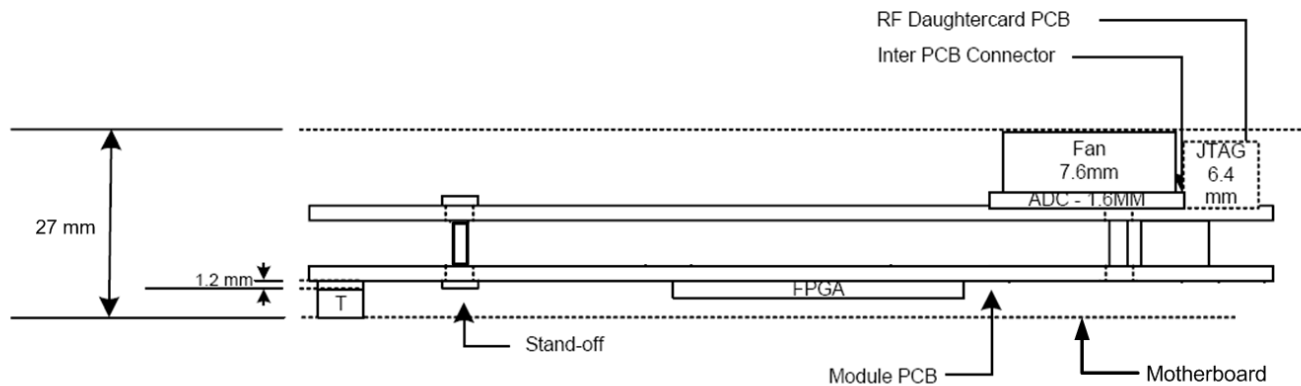


Figure 10: System side view

6 Environment

6.1 Temperature

Operating temperature

- 0°C to +60°C (Commercial)
- -40°C to +85°C (Industrial)

Storage temperature:

- -40°C to +120°C

6.2 Convection cooling

600LFM minimum

6.3 Conduction cooling

The AD484 can optionally be delivered as conduction cooled PMC. The AD484 is compliant to ANSI/VITA 20-2001 standard for conduction cooled PMC.

7 Safety

This module presents no hazard to the user.

8 EMC

This module is designed to operate from within an enclosed host system, which is build to provide EMC shielding. Operation within the EU EMC guidelines is not guaranteed unless it is installed within an adequate host system. This module is protected from damage by fast voltage transients originating from outside the host system which may be introduced through the system.

9 Warranty

	<i>Hardware</i>	<i>Software/Firmware</i>
Basic Warranty (included)	1 Year from Date of Shipment	90 Days from Date of Shipment
Extended Warranty (optional)	2 Years from Date of Shipment	1 Year from Date of Shipment